

# 14/D  
6-18-2  
Robertson  
Arndt

I hereby certify that this correspondence is being deposited by FACSIMILE to the Commissioner of Patents and Trademarks, Washington, DC on June 13, 2002 by Colleen Dew.

Colleen J. DewIN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit 2841

In re application of	:	June 13, 2002
Hormazdyar H. Dalal et al.	:	Examiner: David A. Foster
Serial No. : 09/158,616	:	
Filed: September 22, 1998	:	IBM Corporation
Title: A MULTI-LEVEL ELECTRONIC	:	Dept. 18G/Bldg, 300-482
PACKAGE AND METHOD FOR	:	2070 Route 52
MAKING SAME	:	Hopewell Junction, NY
	:	12533-6531

Amendment

Commissioner for Patents and Trademarks  
Washington, D.C. 20231

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JUN 13 2002

TECHNOLOGY CENTER 2800

Sir:

Kindly amend the claims as follows:

- D1
- 1 1. (thrice amended) A package for containing electronic components, the
  - 2 package comprising:
  - 3 a first circuitized card;
  - 4 a second circuitized card;
  - 5 an interposer interposed between the first and second circuitized cards,
  - 6 the interposer having an opening, the opening in the interposer and the first and
  - 7 second circuitized card forming a cavity for containing at least one electronic
  - 8 component
  - 9 wherein the first circuitized card has a bottom surface and there is at least one
  - 10 component mounted to the bottom surface, and wherein the interposer, first
  - 11 circuitized card, and second circuitized card are circuitized multi-layer organic
  - 12 laminate cards.